



Material Content Data Sheet



Sales Product Name		TLE7185-1E		Issued		21. October 2018		
MA#		MA001185972						
Package		PG-DSO-36-38		Weight*		608.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.970	1.47	1.47	14738	14738
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.01		93	
	non noble metal	zinc	7440-66-6	0.227	0.04		373	
	non noble metal	iron	7439-89-6	4.546	0.75		7468	
wire	non noble metal	copper	7440-50-8	184.568	30.32	31.12	303245	311179
	noble metal	gold	7440-57-5	1.294	0.21	0.21	2126	2126
	encapsulation	organic material	carbon black	1333-86-4	0.800	0.13		1314
plastics	plastics	epoxy resin	-	36.787	6.04		60441	
	inorganic material	silicondioxide	60676-86-0	362.272	59.53	65.70	595211	656966
leadfinish	non noble metal	tin	7440-31-5	5.440	0.89	0.89	8938	8938
plating	noble metal	silver	7440-22-4	0.791	0.13	0.13	1300	1300
glue	plastics	epoxy resin	-	0.723	0.12		1188	
	noble metal	silver	7440-22-4	2.170	0.36	0.48	3565	4753
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com